



5830

Thin-Wire Wedge Bonder

Bond System

| | |
|-------------------|--|
| Wire types | Aluminium und Goldwire 17,5 ... 75 µm on 2"-Spool, motorized wire despooler (optional) |
| Bond head | Wedge-Wedge for thin wire Standard wedges of 1" length, |
| Ultrasonic System | F&K Generator 60/100 kHz further frequencies on request |

Bonder Base

| | |
|----------|--|
| Axes | Working area X/Y-axis 200 x 150 mm; step resolution 0,3 µm Programmable Z axis with 100 mm stroke; step resolution 0,3 µm |
| Hardware | Dual-Core PC with Windows 7 OS, Ethernet, USB 2.0/3.0, LCD Colour Display 22" GigE-CCD-Colour Camera, 5 Mpixel Fully networkable in TCP/IP servers for program archiving |
| Software | From single bonds up to complex programmes, teach-in programming, also in step-and-repeat Loop shapes can be stored in libraries Optionally: pattern recognition with pseudo-error check |

The Thin-Wire version of the automatic wire bonders in our Series 58 featuring exchangeable bond heads.

A fully automatic mode makes it ideally suited for medium-scale production. Parts to be bonded are fed manually by the operator, but the bonds are produced completely without operator influence. Thanks to the built-in pattern recognition.

Single bonds can be made within seconds, making the machine perfect for R&D and pilot manufacturing and medium volume production.